a wire connecting portion fabricated from a metal material having oxidation resistance and electrically connected to the external connection pad;

an electrical contact projection fabricated from a metal material having oxidation resistance and electrically connected to the internal connection pad;

a surface protective film covering the internal wiring and the surface of the semiconductor chip body while contacting the wire connecting portion and the electrical contact projection in a surrounding manner such that a segment of the wire connecting portion and a segment of the electrical contact projection project from the surface protective film; and

a wire electrically connected to the segment of the wire connecting portion for connecting the semiconductor chip to the external terminal, wherein

the electrical contact projection is in a form of a bump and the wire connecting portion substantially has a shape of the bump.

12.   (Amended) A semiconductor device having a chip-on-chip structure in which a secondary chip is overlapped with and joined to a primary chip, wherein

said primary chip comprises

a primary chip body having a surface with internal wiring disposed thereon, at least one surface area of the internal wiring defining an external connection pad and at least one other surface area different from the at least one surface area of the internal wiring defining an internal connection pad, both the external connection pad and the internal connection pad facing in a same direction as the surface of the primary chip body;

a wire connecting portion fabricated from a metal material having oxidation resistance and electrically connected to the external connection pad;

an electrical contact projection fabricated from a metal material having oxidation resistance and electrically connected to the internal connection pad, the electrical contact projection operative to electrically connect the primary and secondary chips together; and

a surface protective film covering the internal wiring and the surface of the